

Notice of References CitedApplication/Control No
09/487,259Applicant(s)/Patent Under
Reexamination
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Page 1 of 1

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*		Document Number	Date	Name	Classification	
		Country Code-Number-Kind Code	MM-YYYY			
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	B	US-				
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	J	US-				
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.